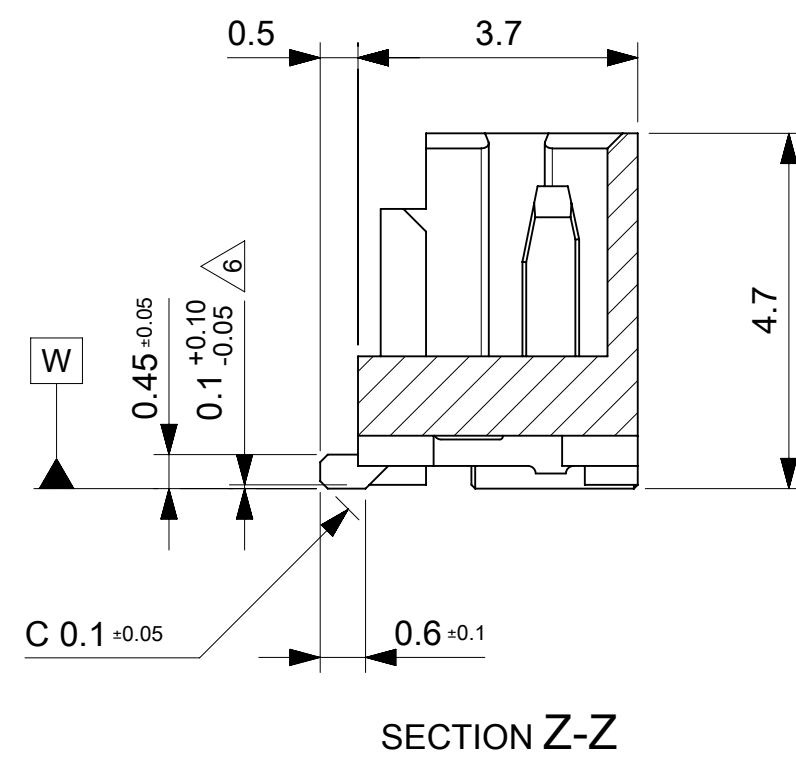
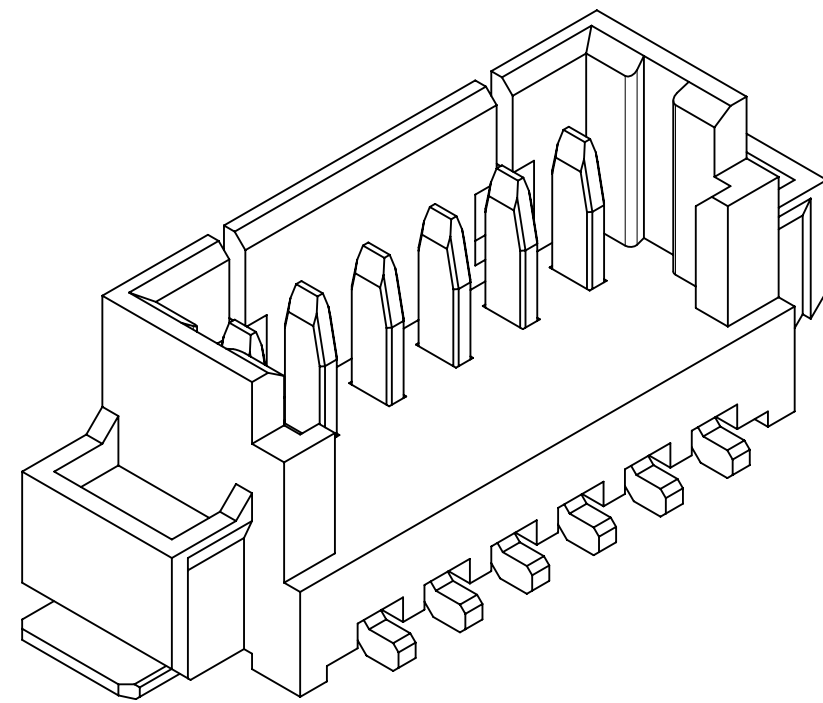
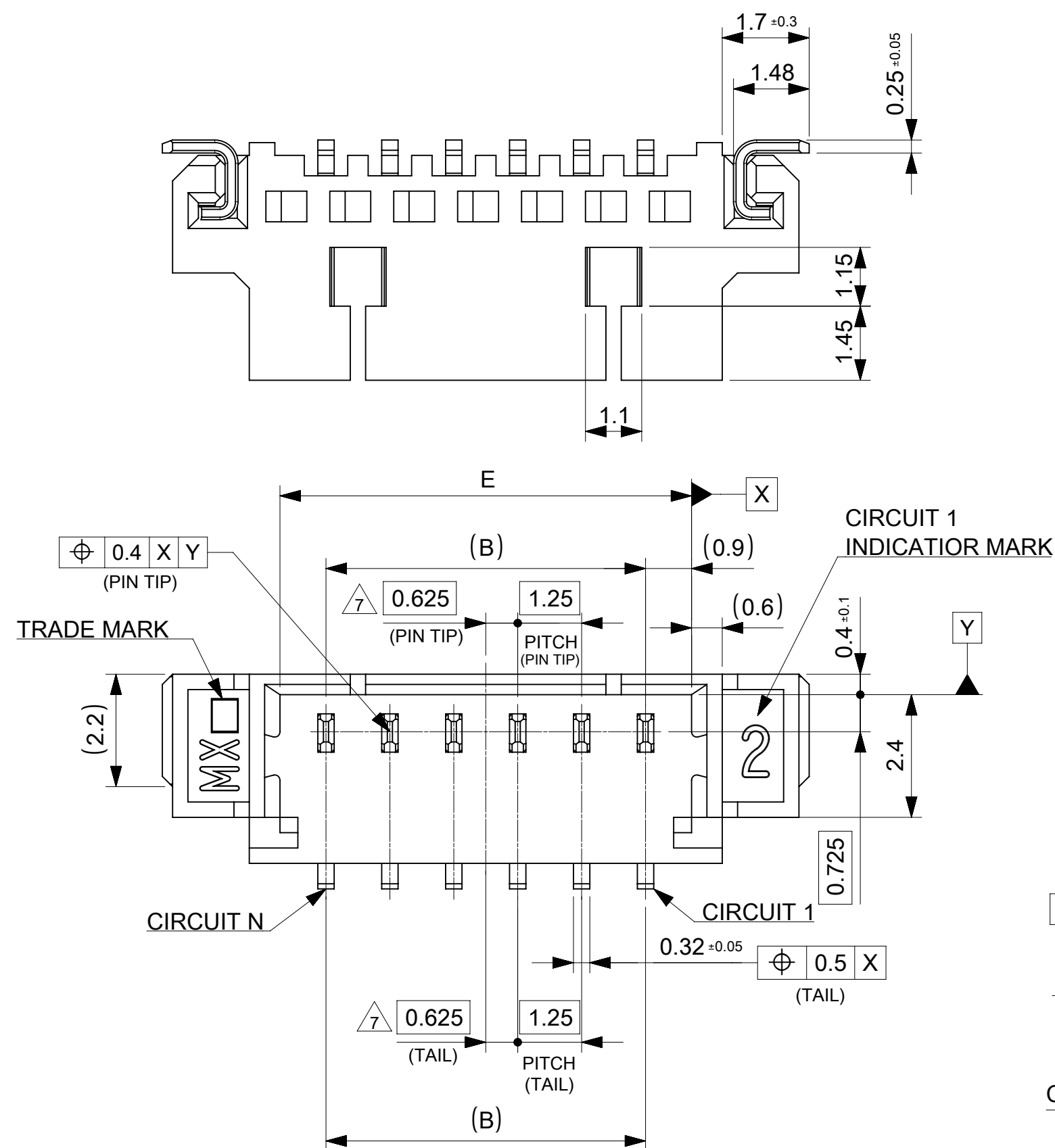
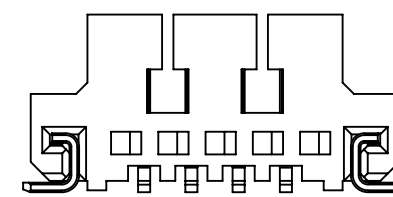


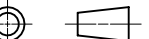
2, 3極形状 (1ロック)
FIGURE OF 2, 3 CIRCUIT (1 LOCK)



4~15極形状 (2ロック)
FIGURE OF 4-15 CIRCUIT (2 LOCKS)

18.6	19.3	20.5	23.5	17.5	23.9	15
17.35	18.05	19.25	22.25	16.25	22.65	14
16.1	16.8	18	21	15	21.4	13
14.85	15.55	16.75	19.75	13.75	20.15	12
13.6	14.3	15.5	18.5	12.5	18.9	11
12.35	13.05	14.25	17.25	11.25	17.65	10
11.1	11.8	13	16	10	16.4	9
9.85	10.55	11.75	14.75	8.75	15.15	8
8.6	9.3	10.5	13.5	7.5	13.9	7
7.35	8.05	9.25	12.25	6.25	12.65	6
6.1	6.8	8	11	5	11.4	5
4.85	5.55	6.75	9.75	3.75	10.15	4
3.6	4.3	5.5	8.5	2.5	8.9	3
2.35	3.05	4.25	7.25	1.25	7.65	2
F	E	D	C	B	A	極數 CIRCUIT SIZE

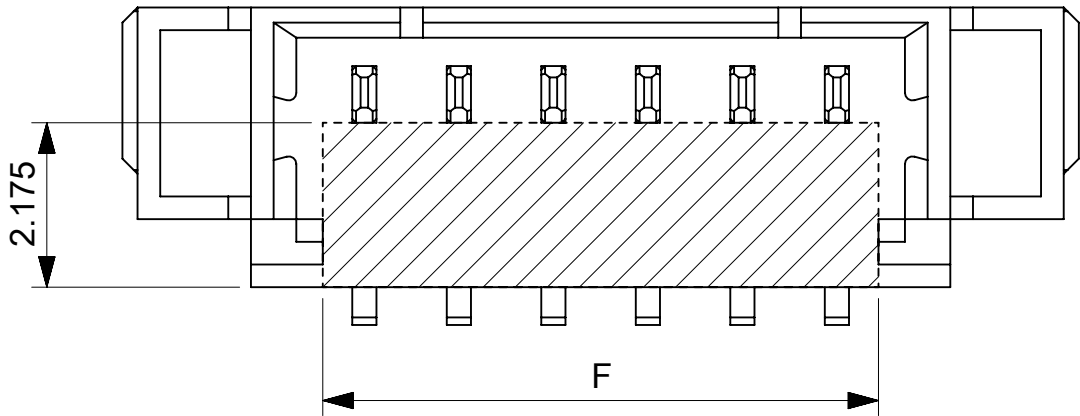
①	TABLE 1	
番号 NO.	部品 PART	材質 MATERIAL
①	ハウジング HOUSING	ポリアミド(PA), UL94V-0, GLASS-FILLED, 色: ナチュラル(ベージュ) POLYAMIDE(PA), UL94V-0, GLASS-FILLED, COLOR: NATURAL (BEIGE)
②	ターミナル TERMINAL	母材 MATERIAL りん青銅 PHOSPHOR BRONZE
		コンタクト部 CONTACT AREA 金めっき: めっき厚は注記15参照 GOLD PLATING PLATING THICKNESS: SEE NOTE 15.
		テール部 TAIL AREA 金めっき GOLD PLATING
		下地めっき UNDER PLATING ニッケルめっき 1.0 micro-meters MIN NICKEL PLATING 1.0 micro-meters MIN
③	ネイル NAIL	母材 MATERIAL りん青銅 PHOSPHOR BRONZE
		テール部 TAIL AREA 無光沢錫めっき 1.0 micro-meters MIN MATTE TIN PLATING 1.0 micro-meters MIN
		下地めっき UNDER PLATING ニッケルめっき 1.0 micro-meters MIN NICKEL PLATING 1.0 micro-meters MIN

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DIMENSION UNITS		SCALE		CURRENT REV DESC:					
mm		NTS							
GENERAL TOLERANCES (UNLESS SPECIFIED)				PICOBLADE 1.25 HEADER ASSY SMT VERTICAL GOLD PLATING TYPE					
ANGULAR TOL ± 3.0 °									
4 PLACES		± 0.2		EC NO: 744677		PRODUCT CUSTOMER DRAWING			
3 PLACES		± 0.2		DRWN: QHE31 2022/06/13					
2 PLACES		± 0.2		CHK'D: AIDA 2023/07/24					
1 PLACE		± 0.2		APPR: MARAI 2023/07/24		DOCUMENT NUMBER 533980002-SD			
0 PLACES		± 0.2		INITIAL REVISION:					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES	
						A2-SIZE		53398	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				DRWN: QHE31 2020/08/03		MATERIAL NUMBER		CUSTOMER	
				APPR: KOMURAKAMI 2021/05/27		SEE CHART OF SHEET3		GENERAL	
								SHEET NUMBER	
								1 OF 4	

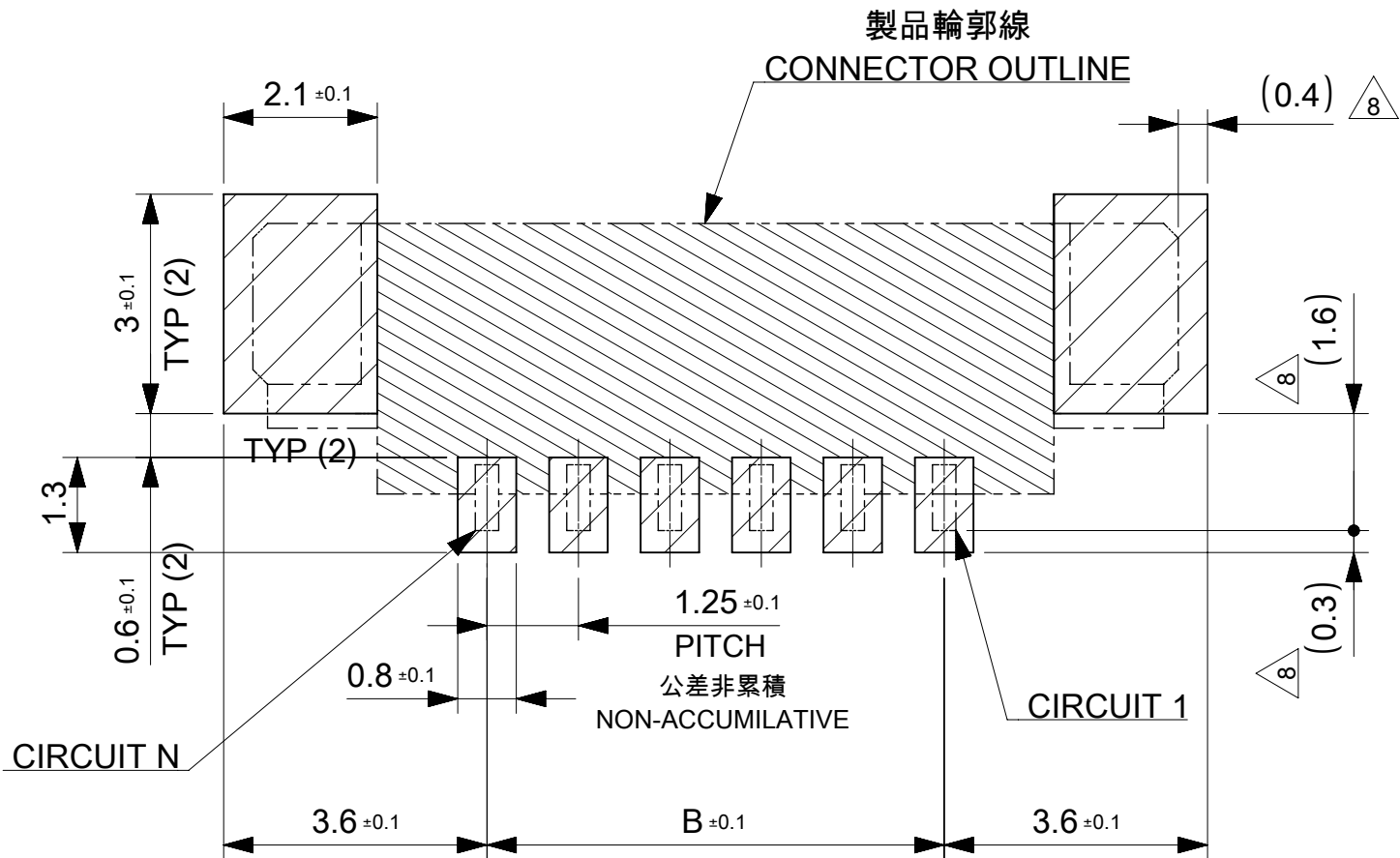
NOTES

- ① 材料および仕上げ（めっき仕様）：TABLE 1参照
MATERIAL AND FINISHES : SEE TABLE 1
- ② 適用製品及び各種仕様書はSHEET 4を参照のこと
REFER TO SHEET 4 ABOUT APPLICABLE PRODUCTS
AND VARIOUS SPECIFICATIONS
3. 梱包形態：SHEET 3 参照
PACKAGING INFORMATION : SEE SHEET 3
4. 本製品は金めっき品です。錫めっき品は533980000-SDをご参照ください
THIS PRODUCT IS GOLD PLATING TYPE.
PLEASE REFER TO 533980000-SD FOR TIN PLATING TYPE.
5. 端子テール部およびネイルの平坦度は0.1以下
COPLANARITY OF TAIL AND NAIL TO BE 0.1 MAX.
- ⑥ 水平面上においてのハウジング底面 W とソルダータール及びネイル底面とのズレ量を示す。
MISALIGNMENT OF SOLDER TAIL AND NAIL FROM W
- ⑦ 偶数極のみに適用
APPLY TO EVEN CIRCUIT PRODUCTS.

DOCUMENT STATUS	P1	RELEASE DATE	2023/07/24	10:03:44
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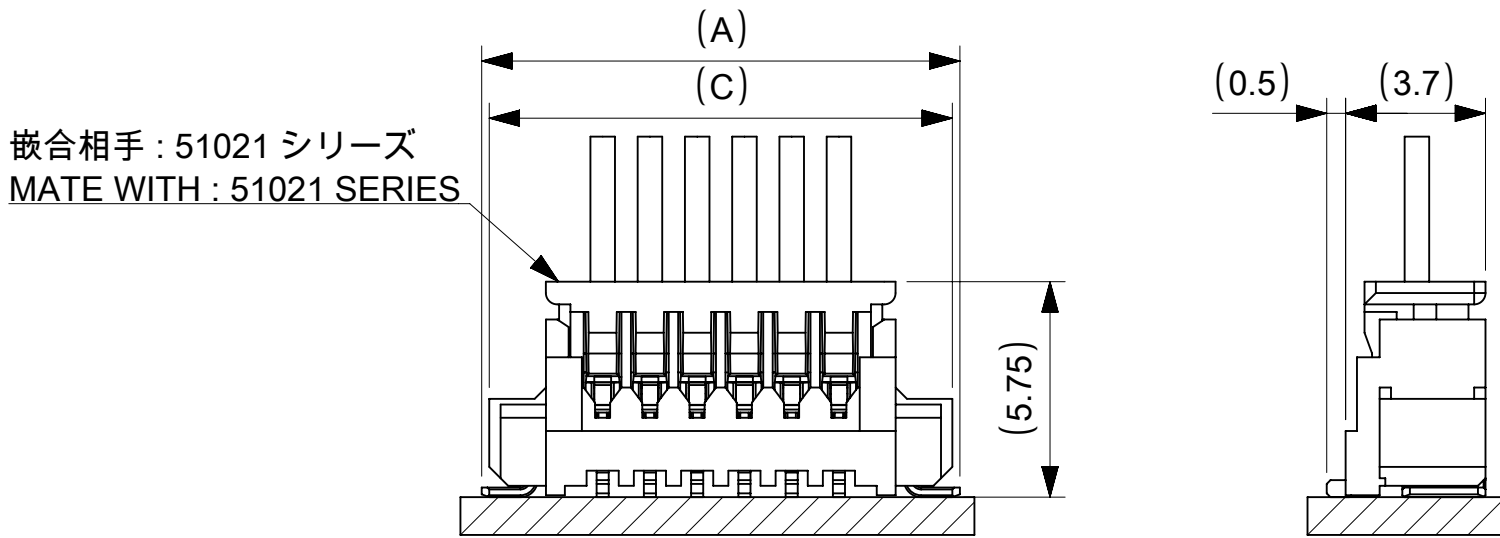
吸着面
VACUUM AREA



推奨基板レイアウト (実装面側)
RECOMMENDED PCB LAYOUT : COMPONENT SIDE

(参考 : 基板厚 1.0 MILLIMETER, メタルマスク厚さ: 0.15 MILLIMETER, マスク開口率:100%)
(REFERENCE : PCB THICKNESS 1.0 MILLIMETER, STENCIL THICKNESS: 0.15 MILLIMETER, APERTURE:100%)

パターン非推奨エリア
PATTERN NOT RECOMMENDED AREA



嵌合図
MATED CONNECTORS

- △₈ コネクタ外形からパッドまでの寸法を示す。
DIMENSIONS FROM CONNECTOR OUTLINE TO PAD
- △₉ 製品の基板実装部以外の金属露出部と基板パターンとの干渉、
および製品と基板上の突起物との干渉が生じないようにご配慮をお願いいたします。
PLEASE TAKE CARE NOT TO CAUSE INTERFERENCE BETWEEN EXPOSED
METAL PARTS EXCLUDING MOUNTING PORTION OF PRODUCT AND PWB PATTERN,
AND INTERFERENCE BETWEEN PRODUCT AND PROTRUSIONS ON PWB.

18.6	19.3	20.5	23.5	17.5	23.9	15
17.35	18.05	19.25	22.25	16.25	22.65	14
16.1	16.8	18	21	15	21.4	13
14.85	15.55	16.75	19.75	13.75	20.15	12
13.6	14.3	15.5	18.5	12.5	18.9	11
12.35	13.05	14.25	17.25	11.25	17.65	10
11.1	11.8	13	16	10	16.4	9
9.85	10.55	11.75	14.75	8.75	15.15	8
8.6	9.3	10.5	13.5	7.5	13.9	7
7.35	8.05	9.25	12.25	6.25	12.65	6
6.1	6.8	8	11	5	11.4	5
4.85	5.55	6.75	9.75	3.75	10.15	4
3.6	4.3	5.5	8.5	2.5	8.9	3
2.35	3.05	4.25	7.25	1.25	7.65	2
F	E	D	C	B	A	極数 CIRCUIT SIZE

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DIMENSION UNITS	SCALE	CURRENT REV DESC:	
mm	NTS		
GENERAL TOLERANCES (UNLESS SPECIFIED)			
ANGULAR TOL	± 3.0 °		
4 PLACES	± 0.2		
3 PLACES	± 0.2		
2 PLACES	± 0.2		
1 PLACE	± 0.2		
0 PLACES	± 0.2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING

EC NO: 744677
DRWN: QHE31
CHK'D: AIDA
APPR: MARAI

2022/06/13
2023/07/24
2023/07/24

INITIAL REVISION:
DRWN: QHE31
APPR: KOMURAKAMI

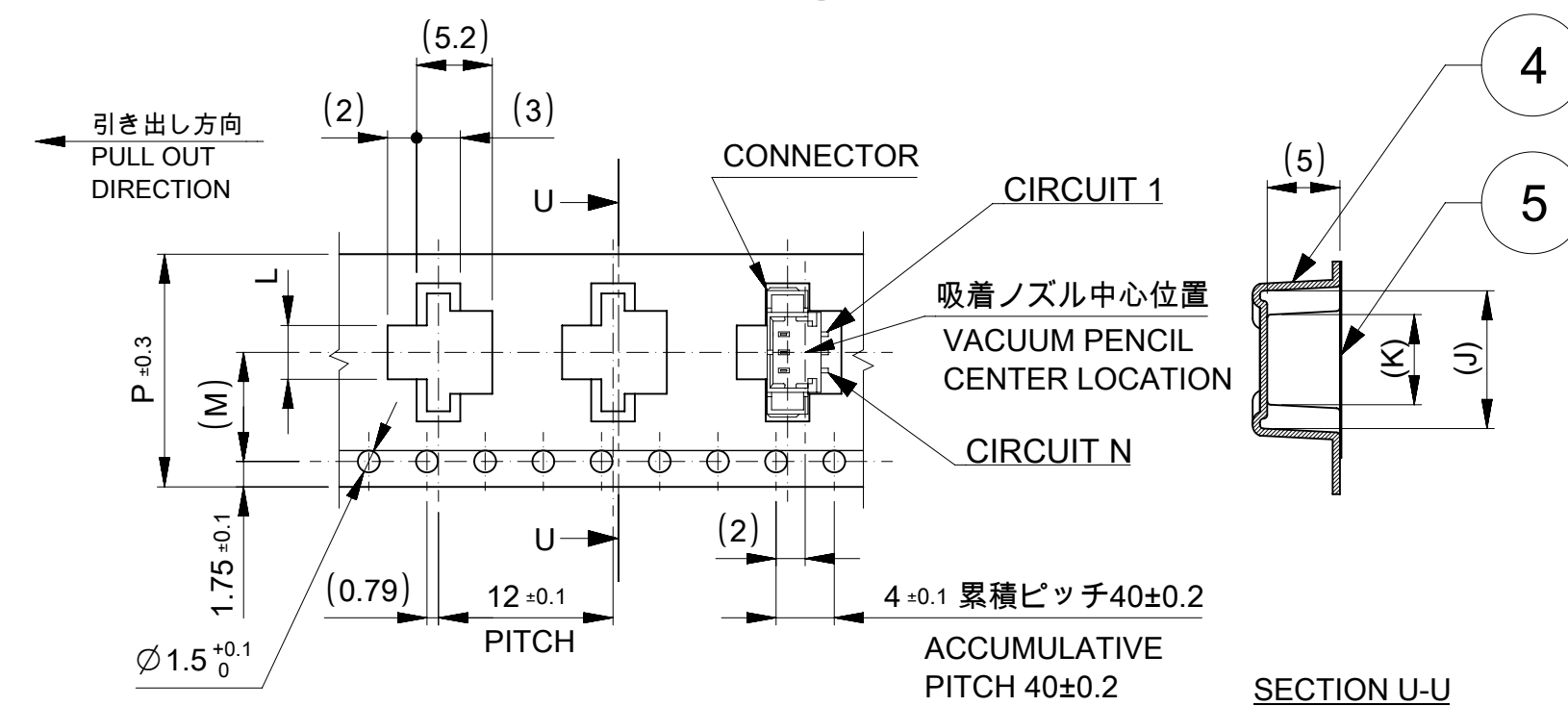
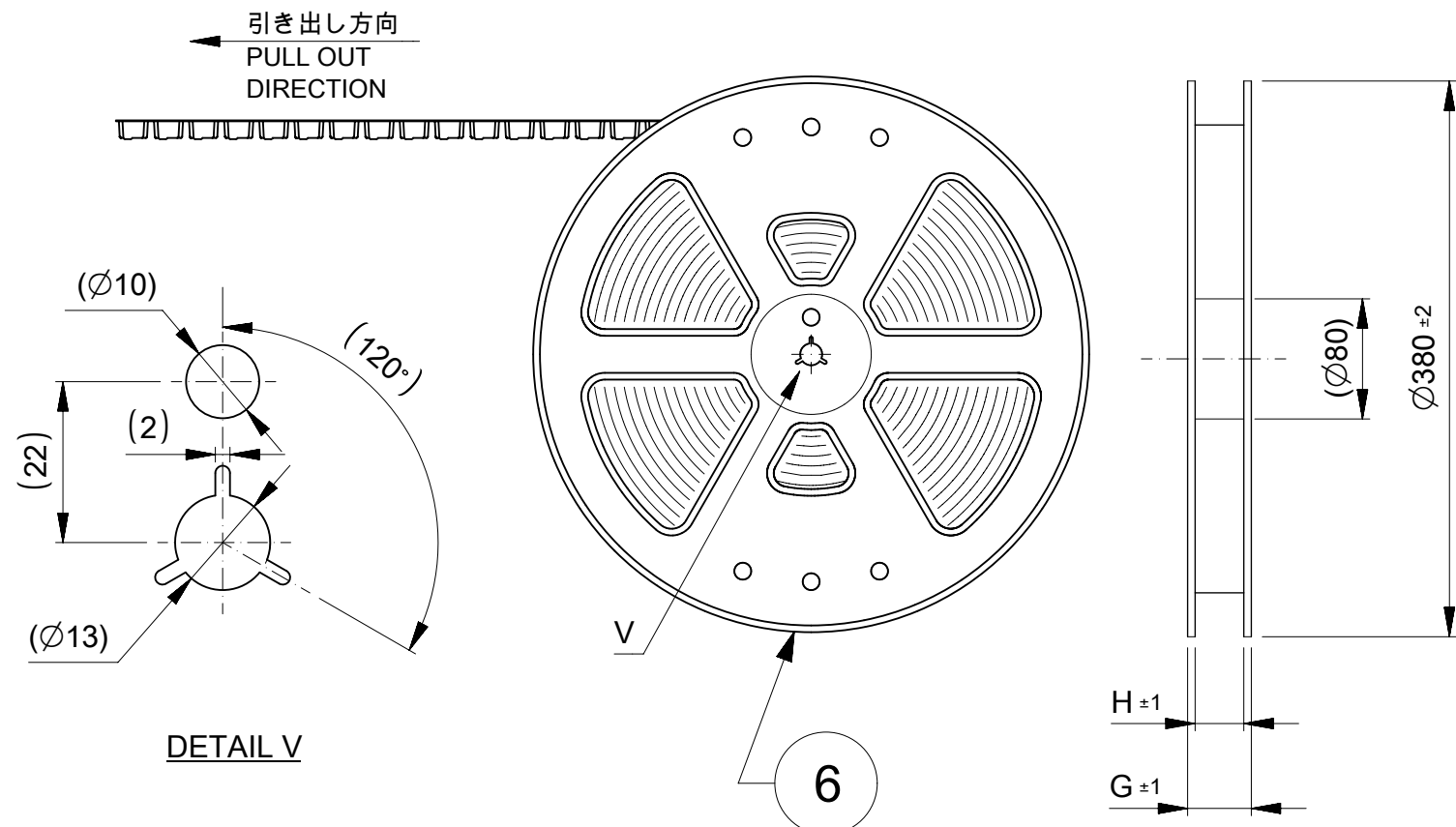
2020/08/03
2021/05/27

molex

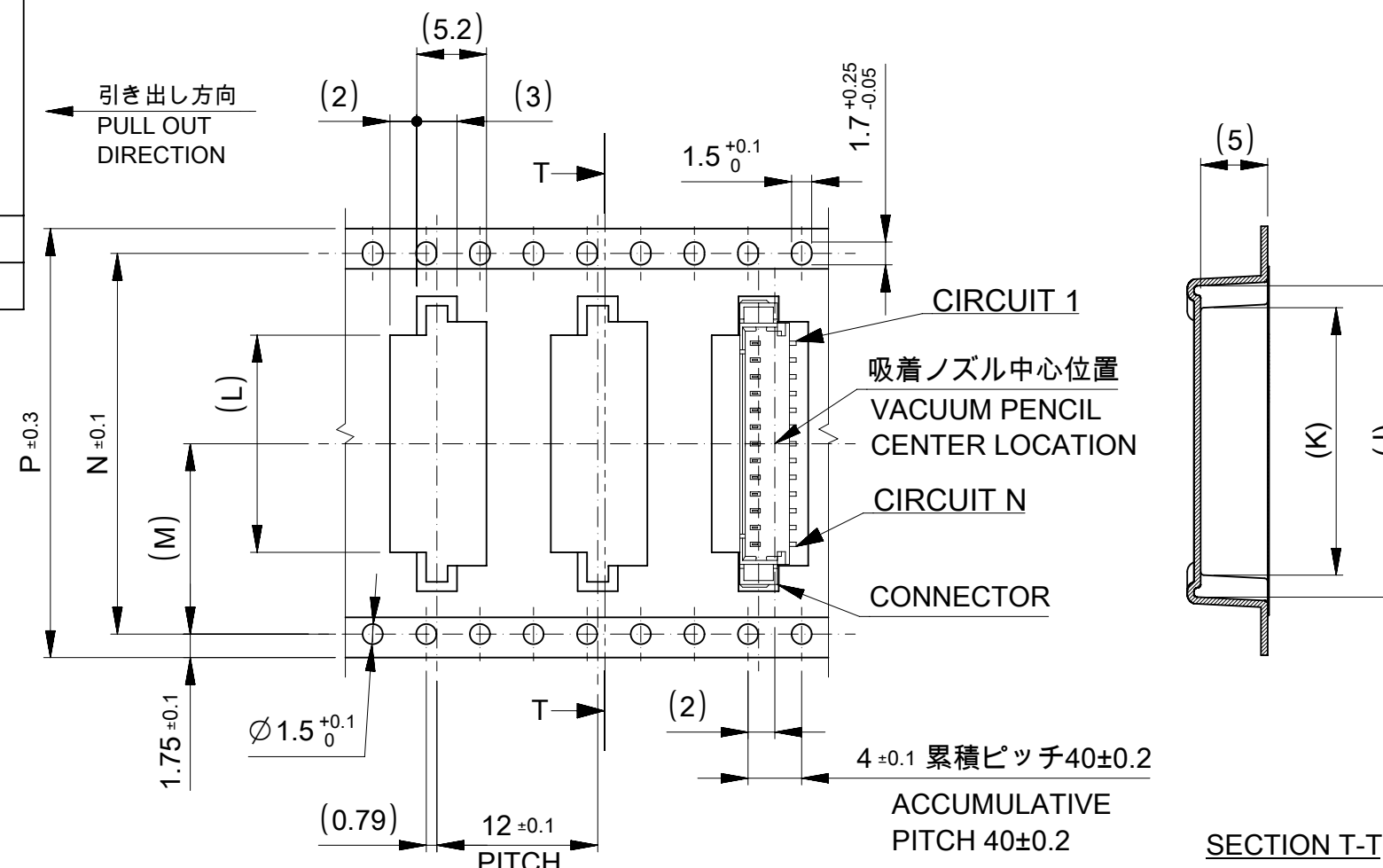
PICOBLADE 1.25
HEADER ASSY SMT VERTICAL GOLD PLATING TYPE

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
533980002-SD	PSD	000	B
MATERIAL NUMBER	CUSTOMER	SHEET NUMBER	
SEE CHART OF SHEET3	GENERAL	2 OF 4	



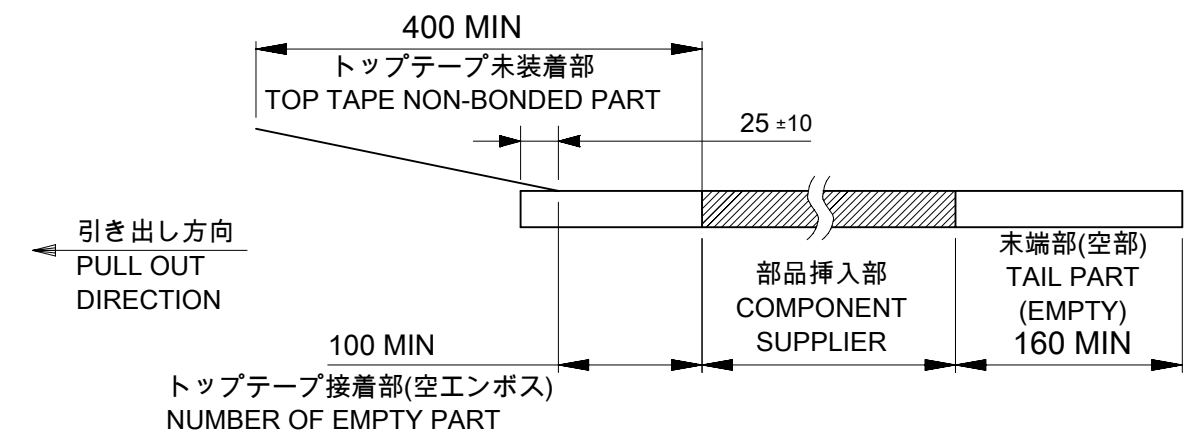
16mm幅(2~3極用) および24mm幅(4~10極用)キャリアテープ
16mm (FOR 2-3 CIRCUIT) OR 24mm (FOR 4-10 CIRCUIT) WIDTH CARRIER TAPE



32mm幅(11~13極用) および44mm幅(13~15極用)キャリアテープ
32mm (FOR 11-13 CIRCUIT) OR 44mm (FOR 13-15 CIRCUIT) WIDTH CARRIER TAPE

NOTES

10. 梱包数量 : 1400個/リール
NUMBER OF CONNECTOR : 1400PCS / REEL
11. リードテープ長さ
LEAD TAPE LENGTH



- △12. 材料：TABLE 2 参照
MATERIAL：REFER TO TABLE 2
13. トップテープの剥離強度はIEC60286-3に準拠
TOP TAPE PELING FORCE IS DEFINED BY IEC60286-3.
14. 本製品は乾燥剤入り、ハイバリア梱包仕様による納品となります。
THIS PRODUCT IS DELIVERED IN A HIGH BARRIER PACKAGE WITH DESICCANT.

TABLE 2

番号 NO.	部品 PART	材質 MATERIAL
④	エンボステープ EMBOSSSED TAPE	MXL生産分：ポリプロピレン(PP) PROCEED BY MXL: POLYPROPYLENE(PP) MXK生産分：ポリスチレン(PS) PROCEED BY MXK: POLYSTYRENE(PS)
⑤	トップテープ TOP TAPE	ポリエチレンテレフタレート(PET)、その他 POLYETHYLENE TEREPHTHALATE(PET), OTHER
⑥	リール REEL	ポリスチレン(PS) <リサイクル材を含む> POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED >

44	40.4	20.2	18.7	20.8	24.5	45.4	49.4	15
			17.45	19.55	23.25			14
32	28.4	14.2	16.2	18.3	22	33.4	37.4	13
			14.95	17.05	20.75			12
			13.7	15.8	19.5			11
24	--	11.5	12.45	14.55	18.25	25.4	29.4	10
			11.2	13.3	17			9
			9.95	12.05	15.75			8
			8.7	10.8	14.5			7
			7.45	9.55	13.25			6
			6.2	8.3	12			5
			4.95	7.05	10.75			4
16	--	7.5	3.7	5.8	9.5	17.4	21.4	3
			2.45	4.55	8.25			2
キャリアテープ幅 p CARRIER TAPE WIDTH p	N	M	L	K	J	H	G	極数 CIRCUIT SIZE

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DIMENSION UNITS		SCALE		CURRENT REV DESC: EC NO: 744677 DRWN: QHE31 CHK'D: AIDA APPR: MARAI INITIAL REVISION: DRWN: QHE31 APPR: KOMURAKAMI			molex PICOBLADE 1.25 HEADER ASSY SMT VERTICAL GOLD PLATING TYPE			
mm		NTS								
GENERAL TOLERANCES (UNLESS SPECIFIED)										
ANGULAR TOL		± 3.0 °					PRODUCT CUSTOMER DRAWING			
4 PLACES		± 0.2								
3 PLACES		± 0.2		DOCUMENT NUMBER			DOC TYPE	DOC PART	REVISION	
2 PLACES		± 0.2								
1 PLACE		± 0.2		533980002-SD			PSD	000	B	
0 PLACES		± 0.2								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER		CUSTOMER		SHEET NUMBER
		A2-SIZE	53398	SEE CHART OF SHEET3		GENERAL		3 OF 4		

B	533985015	533984015	15	
	533985014	533984014	14	
	533985013	533984013	13	
	533985012	533984012	12	
	533985011	533984011	11	
	533985010	533984010	10	
	533985009	533984009	9	
	533985008	533984008	8	
	533985007	533984007	7	
	533985006	533984006	6	
	533985005	533984005	5	
	533985004	533984004	4	
	533985003	533984003	3	
	533985002	533984002	2	
	A	GOLD PLATING THICKNESS 0.38micro-meters MIN	GOLD PLATING THICKNESS FLASH	極数 CIRCUIT
発注番号 ORDER NO.				
梱包形態：エンボス梱包				
PACKAGING：EMBOSSD TAPE AND REEL				
DOCUMENT STATUS		P1	RELEASE DATE	2023/07/24

△2

適合製品および各種仕様書

APPLICABLE PRODUCTS AND SPECIFICATIONS

梱包仕様書 PACKING SPECIFICATION	PART NUMBER				SPECIFICATION NUMBER	
	53398****				SPK-53398-002	
適合嵌合相手 MATE WITH	HOUSING		CRIMP TREMINAL			
	51021****	WIRE SIZE (AWG)	GOLD PLATING THICKNESS		PART NUMBER	
		#28-32	FLASH		500588020	
			0.38 micro-meters		500588025	
		#26-28	FLASH		500798020	
			0.38 micro-meters		500798025	
製品仕様書 PRODUCT SPECIFICATION	510210001-PS PS 000					
アプリケーション仕様書 (取扱説明書) APPLICATION SPECIFICATION	510210000-AS PS 000					

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DIMENSION UNITS	SCALE	CURRENT REV DESC:		molex			
mm	NTS						
GENERAL TOLERANCES (UNLESS SPECIFIED)				PICOBLADE 1.25 HEADER ASSY SMT VERTICAL GOLD PLATING TYPE			
ANGULAR TOL	± 3.0 °	EC NO: 744677 DRWN: QHE31 2022/06/13 CHK'D: AIDA 2023/07/24 APPR: MARAI 2023/07/24		PRODUCT CUSTOMER DRAWING			
4 PLACES	± 0.2			DOCUMENT NUMBER 533980002-SD DOC TYPE PSD DOC PART 000 REVISION B			
3 PLACES	± 0.2						
2 PLACES	± 0.2						
1 PLACE	± 0.2	INITIAL REVISION: DRWN: QHE31 2020/08/03 APPR: KOMURAKAMI 2021/05/27		MATERIAL NUMBER CUSTOMER GENERAL SHEET NUMBER 4 OF 4			
0 PLACES	± 0.2						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING A2-SIZE	SERIES 53398			